



- NOTES:
- PIN PUSHOUT FORCE (9072KG)/2LBS MIN.
 - PIN SOLDERABILITY PER MOLEX SPEC. ES-152.
 - PRODUCT SPEC: PS-70246 APPLIES.
 - WAFER TO BE FLAT WITHIN .003 MM/MM.
 - DIMENSIONS FOR PLATING LOCATION:
 - 5A MEASURE POINT FOR THICKNESS
 - 5B MINIMUM COVERAGE
 - GOLD END OF PIN UNLESS OVERALL PLATED.
 - FINISH:
 - 571 : 15 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 574 : 30 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
 - 544 : 5 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 75 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.

- 573 : 20 MICRO INCHES MIN GOLD PLATE ON CONTACT AND 100 MICRO INCHES MIN TIN PLATE ON SOLDER TAIL BOTH OVER 50 MICRO INCHES MIN NICKEL OVERALL.
8. DIM AT THE CENTRE OF THE SHROUDED WALL SHALL BE 5.91MM MIN. THIS SPEC IS VALID FOR ALL CKT SIZE.
9. MATERIAL:
 HSG: GLASS FILLED PBT, UL94V-0, COLOUR BLACK
 PIN: 0.64MM SQ. PIN PHOSPHOR BRONZE.

OBS. TIN/LEAD P/N EC NO. S2006-0952 DRAWN BY: 2006/04/17 CHKD BY: CHIKKAGESHINI 2006/04/18 APPR: PTLH 2006/04/21	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 3 °	DRAWN BY: JENNIFER DATE: 1987/09/18	CHECKED BY: RWONG DATE: 1987/09/18
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO.		DOCUMENT NO.		SHEET NO.
J		A3		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SDA-70246-**20-25,39-41		1 OF 2

